ABSTRACT OF THE DISCLOSURE

GOLD ALLOY THIN WIRE AND GOLD ALLOY BUMP

To provide a gold alloy thin wire and a bump formed therefrom with a small neck length stably obtained upon the wire breakage after ball bonding, a gold alloy thin wire contains 0.2 to 5000 ppm by weight of Si and the balance of gold and unavoidable impurities. The wire may further contains, other than Si, a total amount of 0.2 to 300 ppm by weight of at least one from the first group of Ca, Be, La, and Ce; or a total amount of 1 to 500 ppm by weight of at least one from the second group of Y, Sc, Sr, Ga, Ge, and In; or a total amount of 2 to 10000 ppm by weight of at least one from the third group of Cu, Pd, Pt, Al, and Mn.

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